United States Patent [19]

Takahashi et al.

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[54] LIGHT-EMITTING DIODE SEMICONDUCTOR CHIP WITH LEADS

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[**] Term: 14 Years

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[57]

CLAIM

The ornamental design for a light-emitting diode semiconductor chip with leads, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light-emitting diode semiconductor chip with leads showing our new design; FIG. 2 is a front elevational view thereof;

FIG. 3 is a side elevational view thereof, as seen from

the right side of FIG. 1;

FIG. 4 is a side elevational view thereof, as seen from the left side of FIG. 1;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

FIG. 7 is a perspective view of a light-emitting diode semiconductor chip with leads showing the second embodiment of our new design;

FIG.8 is a front elevational view thereof;

FIG. 9 is a side elevational view thereof, as seen from the right side of FIG. 7;

FIG. 10 is a side elevational view thereof, as seen from the left side of FIG. 7;

FIG. 11 is a top plan view thereof; and

FIG. 12 is a bottom plan view thereof.





